

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings of claims in the application:

**Listing of Claims:**

1                   1.       (Currently amended) A method for inspecting semiconductor devices  
2 comprising the steps of:  
3                   setting an inspection conditions condition by using semiconductor device design  
4 data chip matrix data and chip size data which are obtained by accessing a design database via  
5 communication means;  
6                   inspecting a semiconductor devices device with these set said inspection  
7 conditions condition;  
8                   using results of this inspection to revise set revising said inspection conditions  
9 condition with said design data by using data obtained by the inspecting; and  
10                  inspecting semiconductor devices using these said revised inspection conditions  
11 condition.

1                   2.       (Currently amended) The method for inspecting semiconductor devices  
2 according to claim 1, wherein said inspection condition comprises information that states  
3 whether or not an area for inspection is in an area in which false alarms tend to occur is added to  
4 inspection conditions set using said design data.

1                   3.       (Currently amended) The method for inspecting semiconductor devices  
2 according to claim 1, wherein said inspection conditions condition set using said design data are  
3 is revised during said revising so that only actual foreign matter is detected based on results of a  
4 review and classification of defects detected during inspection of said semiconductor devices and  
5 so that the percentage of or a false alarms alarm rate is less than or equal to a certain a preset  
6 amount.

1                   4.     (Currently amended) A method for inspecting semiconductor devices  
2 comprising the steps of:  
3                   specifying a semiconductor devices device product name and names of processes  
4 used to process this product and extracting related information from a design data base obtained  
5 by accessing a design database via communication means;  
6                   setting inspection conditions using this said extracted related information;  
7                   inspecting a semiconductor devices device with these said set inspection  
8 conditions;  
9                   ~~using results of this inspection to revise~~ revising said set inspection conditions  
10 ~~using said design data by using data obtained during inspecting;~~  
11                   inspecting semiconductor devices using ~~these said~~ revised inspection conditions;  
12 and  
13                   outputting results of this inspection.

1                   5.     (Currently amended) The method for inspecting semiconductor devices,  
2 according to claim 4, wherein ~~information that states~~ said inspection conditions set at said setting  
3 comprises information whether or not an area ~~for inspection to be inspected~~ is in an area in  
4 which false alarms tend to occur ~~is added to inspection conditions set using said design data.~~

1                   6.     (Currently amended) The method for inspecting semiconductor devices  
2 according to claim 4, wherein said inspection conditions set at said setting ~~using said design data~~  
3 are revised at said revising so that only actual foreign matter is detected ~~based on results of a~~  
4 ~~review and classification of defects detected during inspection of said semiconductor devices and~~  
5 ~~so that the percentage of or a false alarms~~ alarm rate is less than ~~or equal to a certain~~ a preset  
6 amount.

1                   7.     (Currently amended) A method for inspecting semiconductor devices  
2 comprising the steps of:  
3                   setting semiconductor device inspection conditions;

4 detecting defects by inspecting semiconductor devices using ~~these~~ said set  
5 inspection conditions;  
6 classifying ~~these detected defects~~ detected at said detecting by using information  
7 from a database obtained by accessing said database via communication means;  
8 revising said set inspection conditions using ~~these~~ classification results; and  
9 inspecting semiconductor devices using ~~these~~ said revised set inspection  
10 conditions.

1 8. (Original) The method for inspecting semiconductor devices according to  
2 claim 7, wherein images of said classified defects are displayed on a screen.

1 9. (Currently amended) The method for inspecting semiconductor devices  
2 according to claim 7, wherein, in said ~~step of~~ revising said set inspection conditions, reviewing  
3 said classified defects ~~are reviewed~~, and revising said set inspection conditions ~~are revised by~~  
4 using results of ~~this review~~ said reviewing.

1 10. (Currently amended) The method for inspecting semiconductor devices  
2 according to claim 7, wherein, in said ~~step of~~ setting said set inspection conditions, ~~said~~  
3 semiconductor device design data is used.

1 11. (New) A method for inspecting semiconductor devices comprising:  
2 setting inspection conditions by using design data obtained by accessing a design  
3 database via communication means;  
4 inspecting said semiconductor devices with said inspection conditions;  
5 using results of said inspecting to revise inspection conditions with said design  
6 data; and  
7 inspecting said semiconductor devices using said revised inspection conditions,  
8 wherein at least one of said inspection conditions differs by an area inside a chip  
9 to be inspected for said semiconductor devices.

1                   12.   (New) A method for inspecting semiconductor devices according to claim  
2 11, wherein said inspection conditions comprise defect detection sensitivity, and said defect  
3 detection sensitivity differs for the area inside a chip of said semiconductor devices.

1                   13.   (New) A method for inspecting semiconductor devices according to the  
2 claim 11, wherein said inspection conditions comprise pattern pitch of a special filter which cuts  
3 light diffracted from patterns formed on said semiconductor devices and pitches of which differ  
4 by the area inside a chip of said semiconductor devices.

1                   14.   (New) A method for inspecting a semiconductor device comprising:  
2 receiving an identifier for the semiconductor device;  
3 setting inspection conditions for the semiconductor device using design data  
4 obtained by communicating with a design database;  
5 inspecting said semiconductor device for defects with said inspection conditions;  
6 generating revised inspection conditions based on results of said inspecting; and  
7 inspecting said semiconductor device for defects with said revised inspection  
8 conditions,  
9 wherein at least one of the inspection conditions is distinctly set for each area of  
10 the semiconductor device to be inspected.

1                   15.   (New) The method of claim 14 wherein the design database is a physically  
2 remote design database.